

Wafer-Level Packaging Symposium



SPEAKER KIT

FEBRUARY 17-19, 2026 | SAN FRANCISCO, CA, USA



Greetings!

We appreciate you volunteering your time and sharing your knowledge and expertise. We have a mutual stake in the success of the program. Please read over the content carefully.

This kit includes:

- » Due Dates
- » Speaker Checklist
- » Speaker Duties
- » Presentation Tips
- » Conference Information
- » Speaker Forms

The overall theme of the conference is “Formatting Advanced Packaging for the Next Generation”. We ask you to think about how your session connects to the Wafer-Level Packaging industry and how it connects to the central theme. We recommend you link your presentation to this central theme, so attendees will experience all sessions being connected.

We are excited to have you be part of WLPS!

For any questions or concerns, please contact us at: wafer@smta.org | 952-920-7682

CONFERENCE DETAILS

Dates

Conference: February 17-19, 2026

Exhibition: February 17-18, 2026

Professional Development Courses: February 19, 2026

Expo

The expo will be held February 17-18. If your company is interested in being an exhibitor or a sponsor to increase your exposure, please contact us. More information can be found [ONLINE](#).

Program

The most updated program can be found [ONLINE](#). Please let us know if anything needs to be changed. We ask that you promote the conference, expo and courses to your contacts as well. All content is required to be strictly technical. Please refer to the Non-Commercialism Policy included in this kit.

Proceedings

The link to access the PPTs will be distributed via email to attendees following the conference. Proceedings will remain unchanged and will only include the extended abstract and a PDF version of your PowerPoint (if given approval). Proceedings will not be provided in advance.

Registration

All speakers, session chairs and panelists are expected to register at a discounted rate. Please register via the [WLPS REGISTRATION PAGE](#).

Hotel

Hyatt Regency San Francisco Airport
1333 Bayshore Highway, Burlingame, CA 94010
Phone: 650-347-123

Deadline to book: Monday, January 26, 2026

SMTA Rate: Starting at \$199/night +taxes

[Reserve Your Room Now](#)

DUE DATES

DATE DUE

ACTION ITEM

ASAP	Speaker Agreement Form
ASAP	Speaker Biography Form
ASAP	Speaker Copyright Form
JANUARY 30	Extended Abstract & Presentation Slides

[View the Speaker Portal](#)

SPEAKER CHECKLIST

- ☐ Speaker Forms (Agreement, Biography, Copyright)
- ☐ Conference Registration
- ☐ Extended Abstract uploaded to Speaker Portal
- ☐ Presentation Slides uploaded to Speaker Portal
 - Click [HERE](#) to download the required template

SPEAKER RESPONSIBILITIES

**All content is required to be strictly technical.
Please refer to the Non-Commercialism Policy included in this kit.**

Before the conference:

- » **Complete your Speaker Checklist.** Make sure you have turned in all required forms prior to the conference.
- » **Review speaker communication from SMTA Headquarters.** SMTA will be sending documents via email which contain additional details.

Your presentation:

- » **Presentations should be 30 minutes, allowing time at the end for Q&A.** Keynotes and Plenary speakers will have 45 minutes. Your Session Chair will have signs with alerts for 10 minutes and 5 minutes remaining.
- » **Please utilize the podium and lapel microphones.** Even if you feel you are able to project loudly, we often receive feedback that audience members are unable to hear due to ambient room noise.

After the conference:

- » **PowerPoint Presentations will be posted online in PDF format and available for 3 months.** Make sure you have uploaded your presentation to the speaker portal.
- » **Speaker Scores** will be tabulated, evaluated and sent to you after the conference

PRESENTATION TIPS

We understand you may be a seasoned speaker and have your own proven methods of preparation and delivery. The suggestions below may help you to increase or improve your speaker ratings.

Slide Deck Guidelines:

- » Provide an agenda
- » Make sure slides are readable. Use a light color background and one font (change font size and bold/italics for effect)
- » Underscore key points in your presentation with copy, photographs or charts
- » Limit usage of red vs. green on the same slide for those that may be colorblind
- » An effective 25-minute presentation includes 30-35 slides
- » Provide a summary of key points to close
- » Avoid using footers with name, date, slide number etc. as they are viewed as distractions during presentations
- » Practice presentation for delivery and timing

Presentation:

- » Presentations should be technical and not perceived as sales presentations
- » Keep presentations strictly technical and educational
- » Repeat questions
- » Encourage audience participation
- » Do not read slide by slide
- » Provide insight on how audience can transfer information to their job and organizations
- » Leave time for questions

NON-COMMERCIALISM

POLICY: Rev Date March.2021 Ref Section: 8.4

SCOPE: This policy statement encompasses chapter and Headquarters planned events with technical speakers or instructors.

DEFINITIONS: Commercialism is defined as the inclusion in a paper and/or presentation of written or visual references to any company or organization for the purpose of promotion or commercial advantage of the presenting company or the commercial disadvantage of a competing company.

POLICY: All content providers must adhere to the following in any papers and presentations:

1. Company Names, Brands, and Logos

Excessive use of the presenting company's name or logo is prohibited. Using the names or logos of any company supplying goods or services or any competing company is also prohibited. Paper and presentation templates provided by Headquarters shall be used for papers and presentations. Use of brand names, product names, trade names, or trademarks is prohibited. Use of industry accepted generic descriptions or neutral designations such as Type A, Type B, Type C, etc. is acceptable.

2. Products and Services

Discussions of the presenting company's products and/or services are prohibited unless they pertain to the data or information being published. Any discussion of a competitor's products and/or services is prohibited.

3. Comparisons

General comparisons of products and services are prohibited. Generic comparisons that are supported by data may be allowed.

4. Graphics

Any graphic that promotes a product and/or service is prohibited.

5. Confidential Information

Publishing confidential or proprietary information about and/or from other companies, especially competitors, is strictly prohibited.

6. Endorsements

Any inference that the SMTA endorses or approves any company, product, service, or equipment is strictly prohibited.

7. Corrective Action

Authors will be asked to correct papers and/or presentations that violate the policy as defined above. Headquarters and chapters reserve the right to reject any paper and/or presentation for violating this policy.



Speaker Agreement

Please complete & return form immediately!

I agree to the SMTA Non-Commercialism Policy for presentations.

I agree to follow the SMTA Format Requirements on PPT.

I agree to submit my materials and presentation for review by the deadline.

☐ I agree to all of the above and accept the Technical Committee's invitation to present

Signature: _____

This speaker agreement:

- 1) Confirms that you or a co-author will attend and present at the **Wafer-Level Packaging Symposium**
- 2) Verifies your current contact information for conference correspondence
- 3) Activates your record to receive the speaker discount on your conference registration.

****Please Note* If you are the contact only and the speaker has not been finalized, please complete the form with your information and add TENTATIVE after your name. We will need a Speaker Agreement from the final speaker when identified.***

Use (X) to indicate your role(s): ☐ Speaker ☐ Panelist ☐ Chair ☐ Co-Chair

(X) for all that apply: ☐ Ph.D. ☐ Professor ☐ P.E. Other: _____

Name: _____

Company: _____

Position: _____

City: _____

Email: _____

State/Country: _____

Phone: _____

Zip/Country Code: _____

Paper Title(s) 1. _____

2. _____

Please email completed form ASAP to wafer@smta.org



Speaker Biography

To help us give complete introductions for each speaker, we ask that you use the lines below to furnish us with a short biography. Please include your job title, job description, previous work history, awards/associations, and publications/patents. [Limit 125-150 words]

☐ Please indicate if you would like to reuse your biography that has already been submitted for a past SMTA/WLPS event (limit two years).

Past Event Name: _____

Past Event Year: _____

Name: _____

Company: _____

Event Name: Wafer-Level Packaging Conference

Paper/Presentation Title(s): _____

Please email completed form to wafer@smta.org



Copyright & Publication Form

PART I. Copyright

Under the terms of the U.S. Copyright laws, SMTA/WLPS, as publisher, is required to obtain a copyright transfer from all authors of extended abstracts published in the Proceedings. Please complete and return this copyright assignment form or your company's standardized form with your extended abstract.

An author, company or the U.S. Government will maintain all proprietary right, such as patents and the right to the extract, in part or whole, the material for future use. SMTA/WLPS, in turn, grants the non-exclusive right of republication subject to adding the following credit:

***"Originally published in the proceedings of the
Wafer-Level Packaging Symposium,
in February 2026."***

Please note that all extended abstracts will be published in conference proceedings and SMTA Knowledge Base.

Additionally, SMTA/WLPS strongly encourages that you do not post or upload your paper onto outside forums or websites. However, if you do, we ask that you kindly notify us of any such postings.

PART II. Publication

Permission is hereby granted to the SMTA to post the speaker's PowerPoint presentation in a secured PDF format on the SMTA website for conference attendees to access for no longer than three (3) months following the symposium.

☐ YES ☐ NO

Paper/Presentation Title: _____

Author Signature: _____

PRINT Author(s) Name(s): _____

PRINT Company Name: _____

Company Approval Signature: _____

Title of Company Authority: _____

Date: _____

Please return this form to wafer@smta.org ASAP.

Speaker Consent for Recordings

I authorize The Wafer-Level Packaging Symposium and its agents, on behalf of SMTA to make audio and video recordings of my presentation or program described below and to use my name, photograph, and biographical information in connection with the reproduction, distribution and promotion of the Presentation and the Recordings. I understand that SMTA will credit me as the author or source of the Presentation.

I retain any copyrights I may have in the Presentation. Nothing in this document shall limit my rights to publish or use the Presentation as I see fit. I agree that SMTA will own the Recordings and other rights therein.

Neither my Presentation nor the grant of rights I have made to SMTA in this document infringes or violates any copyright or other right of, or breaches any obligation I have, any other person or entity.

Event Title: The Wafer-Level Packaging Symposium

Conference Dates: February 17-19, 2026

Location: Burlingame, CA, USA

Signature

Date

Print Name

Wafer-Level Packaging Symposium



FEBRUARY 17 - 19, 2026
SAN FRANCISCO, CA, USA

Extended Abstract Format Requirements

Non-Commercialism Policy:

- Extended abstracts and PowerPoint presentations perceived as sales presentations will not be accepted by the Technical Committee
- To avoid commercialism please do NOT include: logo, website, address, etc. of your company on the extended abstract
- Use generic name (example: Product A; Process A) not specific company model numbers, to identify equipment or processes
- Limit TM(Trademarks) and ©(Copyrights) to references at the end of the extended abstract
- Promote your company by letting the technical characteristics of your new product or process speak for themselves

Reasons for Non-Acceptance:

- Commercialism or non-objectivity that cannot be corrected with editing
- Previously published paper or similarity to previously published paper
- Inadequate technical content; lacks supportive test data
- Comparisons to products produced by competing companies
- Subject not related to the interests of the *Wafer-Level Packaging* audience
- Extended abstracts that do not use SMTA format requirements

Submit Extended Abstracts:

- In a Word document (required)
- Email Word document to wafer@smta.org
- Embed your figures, tables, graphics, and photos directly into your word document for the best possible reproduction of your paper in the proceedings

Copyright and Publication Form:

- SMTA retains copyright for all published material in conference proceedings
- Complete and return the Copyright & Publication Form via email when you submit your extended abstract. A completed form is required prior to the start of the conference
- When a request for reprint is received, SMTA will contact the author for permission
- SMTA strongly encourages that you do not post or upload your paper onto outside forums or websites. However, if you do, we ask that you kindly notify SMTA of any such postings

Wafer-Level Packaging Symposium



FEBRUARY 17 - 19, 2026
SAN FRANCISCO, CA, USA

Extended Abstract Format Requirements

Extended Abstract Format (see *SAMPLE* that follows for reference)

- Must be a 3-4 pages (including tables, graphs, images, etc.) and include the following:
 1. Abstract / Introduction
 2. 2-6 Keywords
 3. Discussion of methodology used
 4. Greater than 2500 words - Less than 5000
 5. Results data obtained
 6. May include Figures
 7. Conclusion
 8. Acknowledgements (*optional*)
 9. References
 10. Appendix, if needed

Layout

- Paper must be:
 - Single space
 - 2 columns with .25 space between columns
- Illustrations and tables may be placed in the body of text or at the end of your extended abstract
- References should appear as a separate section at the end

Format

Title and Author(s)

- Center PAPER TITLE in all Title Case letters - **USE 14PT BOLD TIMES NEW ROMAN**
- Center Author(s) Company, City, ST, Country, Email (required) Use 12pt Times New Roman
- See Outline and *SAMPLE* that follows for reference

Margins and Spacing

- 0.75 inches margins on all 4 sides of paper.
- 2 column format with a 0.25 inches spacing between columns

Text

- All body text - 10pt. Times New Roman or equivalent 'serif font'
- Justify / block text - no indents for paragraphs
- HEADINGS - flush left, all capital letters; **bold 10pt. Times New Roman**
- Subheadings Flush Left; capitalize the First Letter of Each Word; use **bold 10pt. Times New Roman**
- No line spacing between headings, subheadings and body text
- When using British-American units of measure, give metric equivalent (in parentheses)
- Do NOT number pages. They will be numbered for the Table of Contents

Reference Section (see next page for layout)

***Updated as of September 1, 2018**

Reference Section*

[33] S.K. Kang, Paul Lauro, Da-Yuan Shih, Donald W. Henderson, Timothy Gosselin, Jay Bartelo, Steve R. Cain, Charles Goldsmith, Karl J. Puttlitz, and Tae-Kyung Hwang, "Evaluation of Thermal Fatigue Life and Failure Mechanisms of Sn-Ag-Cu Solder Joints with Reduced Ag Contents," *Proceedings of Electronic Components and Technology Conference*, 661-667, Las Vegas, NV, 2004.

- Reference number
[33] - in [brackets]
- Author names
S.K. Kang - author first name or first initial and last name (author names as they appear in the original citation)
-
- Paper title
"Evaluation of Thermal Fatigue Life and Failure Mechanisms of Sn-Ag-Cu Solder Joints with Reduced Ag Contents," - "paper title in parentheses"
- Conference proceedings title
Proceedings of Electronic Components and Technology Conference, title in italics (optional formats *Proceedings of 54th ECTC*; *Proceedings of 54th Electronic Components and Technology Conference*)
- Page number range
661-667, - page number range (pp. 661-667 is an optional format)
- Conference location (optional)
Las Vegas, NV
- Date
2004 (June 1-4, 2004 date and month optional if available)

Outline of SMTA Format Required

Title: Title Case, BOLD
[14 point, TIMES NEW ROMAN & CENTERED]

Insert 1 blank line

Authors name(s)

Company

ST, Country

Email (no hyperlink) (minimum of one contact is required)
(12 point Times New Roman - no bold)

Insert 2 blank lines

Margins:

Top, bottom & sides 0.75 inches

If using A4 paper – leave a 1.50 inch margin on bottom

Two-column format; 0.25 inch space between columns

Text:

10 point Times Roman font; single-spaced

Text fully justified (no ragged right edge)

Block paragraphs (no indents)

Omit page numbers - they will be inserted electronically

Key words: 2 to 6 keywords after abstract (no bold)

HEADINGS: ALL CAPS; bold and left-justified

Subheadings

First Letter of Each Word in Caps; bold and left-justified.

No line spacing under any headings.

Single line spacing between paragraphs

Tables/Figures/Photos/Graphics Titles (see examples):

Use **BOLD**, 10 point Times New Roman; flush left. Illustrations and tables may appear in the body of text or be placed at the end of your paper. PLEASE NOTE: For the best possible reproduction of your paper in the Proceedings CD-ROM, **embed your color figures and color graphics/photos** directly into your word document.

Use only white backgrounds for text and figures for good contrast/readability. (Proceedings CD-ROM is in color)

REFERENCES

Use superscript numbers¹ or brackets [2] for references in text. **Do NOT use hyperlinks in text to link to References.**

Place references at end of the paper.

Fully justify REFERENCES – **Do NOT include hyperlinks to websites or publications.** See SAMPLE paper.

Our goal for the Proceedings is to have it appear as if it were created and edited as a uniform publication. Minor deviations won't be noticed but a uniform appearance contributes to the professionalism of the conference.

Example of table or graphic and caption in a paper:

Table 1. Cu Dissolution DOE Matrix

		Contact Time Replicates (secs)					
Exp. #	ALLOY	1	2	3	4	5	6
1-1	Sn-Pb	30	30	30	30	30	30
		50	50	50	50	50	50
1-2	SAC405	30	30	30	30	30	30
		50	50	50	50	50	50
1-3	SAC305	30	30	30	30	30	30
		50	50	50	50	50	50
1-4	Sn-Cu + Ni (1)	30	30	30	30	30	30
		50	50	50	50	50	50
2-1	Sn-Ag-Cu + Bi	30	30	30	30	30	30
		50	50	50	50	50	50
2-2	Sn-Ag-Cu + Sb	30	30	30	30	30	30
		50	50	50	50	50	50
2-3	Sn-Cu + X/Y	30	30	30	30	30	30
		50	50	50	50	50	50
2-4	Sn-Cu + Ni (2)	30	30	30	30	30	30
		50	50	50	50	50	50
DOE RUNS		16	16	16	16	16	16
TOTAL DOE RUNS		96					

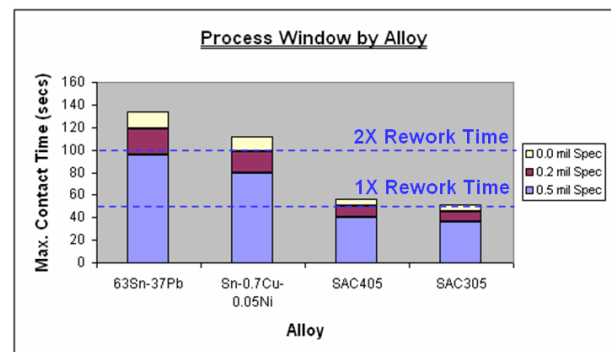


Figure 1. PTH Process Window by Alloy

EXAMPLE of placement of a table (or graphic) that will not fit in one column.

(You may also place all large tables and graphics is an APPENDIX at end of the paper after your REFERENCES)

The third development stage was to build the actual notebook or desktop production motherboard in a lead-free configuration and perform the full battery of board level and system level testing. One notable discovery in this stage was that torsion testing of a notebook motherboard could result in PCB pad cratering due to strain from the high modulus SAC alloy; this was consistent with work from others [6]. As a result some BGA components on notebook products required partial underfilling (or edge glue) to prevent such failures. Such techniques are now fairly common for lead-free assemblies [7]. Without getting into great detail, it can be said that in the course of this extensive two year effort many lead-free issues were discovered and each was resolved prior to launching of the consumer lead-free products.

Since 2005 many tens of millions of lead-free products have been produced and field results show the reliability to be as good (and in many cases better) than the leaded products they replaced. However, one issue did escape this qualification process. Over time it was discovered by Dell [8] and others [9, 10, 14] that the immersion silver surface

business products that may be exposed to such harsh environments (this would include server products).

DISCUSSION OF CHALLENGES

All of this previous experience with converting notebook and desktop products to lead-free was leveraged in taking the next step of converting the complex and challenging class A server products to lead-free. An effective way to start with implementation of any major product or manufacturing change is to consider all the differences from what was previously known and the impact these differences may have on the final product. In this case the primary gaps in transitioning from a lead-free consumer product to a lead-free server are shown in Table 1.

It is also helpful to understand any constraints that may exist. Some constraints at Dell's EMs include the fact that nitrogen reflow was not widely available and no-clean solder flux was required. Without a nitrogen blanket one can expect heavier oxidation of the surfaces to be soldered. In addition, the no-clean fluxes are not as active as the water

Table 1. Differences in a lead-free server compared to transitioning lead-free client products.

Change/Challenge	Risk	Action
PCB thickness increase (from 0.062" to 0.092 or greater)	Incomplete hole fill in wave	Improve wetting with flux, alloy choice, and/or increase temp
	Increased thermal stress on PTHs	Ensure PTH components can survive increased temp
1-3 additional processor sockets are required per board.	More thermal energy needed to achieve consistent solder joints can cause heat damage.	Reduce z-axis CTE and/or increase Cu thickness.
All boards require 2 side SMT + wave solder.	Solderability of PTH degrades with 2 nd side reflow	Ensure surface finish has good solderability and PCB can handle added heat stress.
In circuit test strain limits could be larger with thicker boards.	ICT stress must be minimal to prevent BGA fracture	Ensure a robust surface finish that remains solderable after 2 heat cycles.
Immersion silver surface finish eliminated due to corrosion risk	Alternative finish must meet ICT and solderability requirements	Ensure low contact resistance on test points.
PCB laminate may change from what was used on DT and NB products.	Thermal cycle life of the BGA components can change	Investigate several alternatives (OSP, ImSn, ENIG, and LF HASL)
Larger and heavier assemblies	Shock/vibration differences	Build test vehicle and run thermal cycle testing
PTH rework time is longer	Cu dissolution can reduce knee thickness below specification.	Test final assemblies using shock/vibration/HALT
		Select rework alloy and optimize process to reduce copper dissolution

finish selected for lead-free PCBs had the susceptibility to creep corrode when used in high sulfur and high humidity environments. An IPC investigation is currently underway to develop test methods to better predict sulfur based corrosive environments, while silver manufacturers are actively working to improve their ImAg surface finishes. However, until such time that ImAg is proven to not creep corrode, Dell will not employ this surface finish for critical

soluble fluxes, therefore reducing the oxides is more difficult. Another constraint is to ensure that all IPC 610D solder joint inspection criteria are met (some papers have been written that suggest that hole fill requirements could be reduced while still maintaining sufficient reliability [11] but there is insufficient data at this time to support such a change in specifications). A further constraint is that components with ball pitch as low as 0.8 mm and peripheral

Speaker Name (Click to insert your text)

Company/Organization (Logo on title page only)

Contact Information (Phone & email)

Use Arial (or similar) font; use **bold** & *italics* for emphasis;

do not use font size smaller than 24pt for best reading from back of room

- Limit text per slide - repeat heading & use two or more slides if necessary; 9 lines of text per slide and 25-30 slides maximum
- White/light background with dark text recommended
- Do not insert company name, logo, or website in footers; © only

Outline/Agenda

- **Introduction**
- **Discussion Topics**
- **Results of Experiments**
- **Conclusions**
- **Acknowledgements (*optional*)**
- **Q & A**

Thank You!

Optional -

- **Speaker contact info (click to insert)**
- **Brief speaker bio**